

April 2001 Revised September 2001

# **FIN1019**

# 3.3V LVDS High Speed Differential Driver/Receiver

### **General Description**

This driver and receiver pair are designed for high speed interconnects utilizing Low Voltage Differential Signaling (LVDS) technology. The driver translates LVTTL signals to LVDS levels with a typical differential output swing of 350mV and the receiver translates LVDS signals, with a typical differential input threshold of 100mV, into LVTTL levels. LVDS technology provides low EMI at ultra low power dissipation even at high frequencies. This device is ideal for high speed clock or data transfer.

### **Features**

- Greater than 400Mbs data rate
- 3.3V power supply operation
- 0.5ns maximum differential pulse skew
- 2.5ns maximum propagation delay
- Low power dissipation
- Power-Off protection
- 100mV receiver input sensitivity
- Fail safe protection open-circuit, shorted and terminated conditions
- Meets or exceeds the TIA/EIA-644 LVDS standard
- Flow-through pinout simplifies PCB layout
- 14-Lead SOIC and TSSOP packages save space

### **Ordering Code:**

Order Number	Package Number	Package Description	
FIN1019M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow	
FIN1019MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	

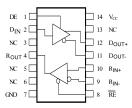
Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### **Function Table**

Inputs				puts	
R <sub>IN</sub> _		RE	R <sub>OUT</sub>		
H	ı	L	I	-	
L		L	ŀ	+	
X		Н	2	7	
Fail Safe Condit		L	Н		
D <sub>IN</sub>		DE	D <sub>OUT+</sub>	D <sub>OUT</sub>	
L		Н	L	Н	
Н		Н	Н	L	
X		L	Z	Z	
Open–Circuit or Z		Н	L	Н	
	R <sub>II</sub> F L X	R <sub>IN</sub> _ H L X Condition	R <sub>IN-</sub>   RE	R <sub>IN</sub> _         RE         R <sub>C</sub> H         L         L           L         L         H           X         H         Z           Condition         L         H           DE         D <sub>OUT+</sub> H           H         L         H           H         H         H           L         Z           t or Z         H         L	

H = HIGH Logic Level Z = High Impedance L = LOW Logic Level X = Don't Care Fail Safe = Open, Shorted, Terminated

# **Connection Diagram**



### **Pin Descriptions**

Pin Name	Description	
D <sub>IN</sub>	LVTTL Data Input	
D <sub>OUT+</sub>	Non-inverting LVDS Output	
D <sub>OUT</sub>	Inverting LVDS Output	
DE	Driver Enable (LVTTL, Active HIGH)	
R <sub>IN+</sub>	Non-Inverting LVDS Input	
R <sub>IN</sub>	Inverting LVDS Input	
R <sub>OUT</sub>	LVTTL Receiver Output	
RE	Receiver Enable (LVTTL, Active LOW)	
V <sub>CC</sub>	Power Supply	
GND	Ground	
NC	No Connect	

### **Absolute Maximum Ratings**(Note 1)

#### Supply Voltage (V<sub>CC</sub>) -0.5V to +4.6V LVTTL DC Input Voltage ( $D_{IN}$ , DE, $\overline{RE}$ ) -0.5V to +6V LVDS DC Input Voltage (R<sub>IN+</sub>, R<sub>IN-</sub>) -0.5V to 4.7V LVTTL DC Output Voltage (R<sub>OUT</sub>) -0.5V to +6VLVDS DC Output Voltage ( $D_{OUT+}$ , $D_{OUT-}$ ) -0.5V to 4.7VLVDS Driver Short Circuit Current (I<sub>OSD</sub>) Continuous LVTTL DC Output Current (I<sub>O</sub>) 16 mA Storage Temperature Range ( $T_{STG}$ ) -65°C to +150°C

 $\label{eq:max_Junction} \begin{aligned} &\text{Max Junction Temperature } (T_J) \\ &\text{Lead Temperature } (T_L) \end{aligned}$ 

(Soldering, 10 seconds) 260°C ESD (Human Body Model) ≥ 6500V ESD (Machine Model) ≥ 300V

# Recommended Operating Conditions

 $\begin{array}{ll} \mbox{Supply Voltage (V$_{CC}$)} & 3.0 \mbox{V to } 3.6 \mbox{V} \\ \mbox{Input Voltage (V$_{IN}$)} & 0 \mbox{ to } \mbox{V}_{CC} \end{array}$ 

Magnitude of Differential Voltage

 $\begin{array}{ll} (|V_{ID}|) & 100 \text{ mV to V}_{CC} \\ \text{Common-Mode Input Voltage (V}_{IC}) & 0.05 \text{V to 2.35V} \\ \text{Operating Temperature (T}_{A}) & -40 ^{\circ}\text{C to +85}^{\circ}\text{C} \\ \end{array}$ 

Note 1: The "Absolute Maximum Ratings": are those values beyond which damage to the device may occur. The databook specifications should be met, without exception, to ensure that the system design is reliable over its power supply, temperature and output/input loading variables. Fairchild does not recommend operation of circuits outside databook specification.

### **DC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

150°C

Symbol	Parameter	Test Conditions	Min	Typ (Note 2)	Max	Units
LVDS Diffe	rential Driver Characteristics	-				
V <sub>OD</sub>	Output Differential Voltage		250	350	450	mV
$\Delta V_{OD}$	V <sub>OD</sub> Magnitude Change from				25	mV
	Differential LOW-to-HIGH	$R_L = 100\Omega$ , See Figure 1			23	liiv
Vos	Offset Voltage		1.125	1.25	1.375	V
$\Delta V_{OS}$	Offset Magnitude Change from				25	mV
	Differential LOW-to-HIGH				23	IIIV
I <sub>OZD</sub>	Disabled Output Leakage Current	V <sub>OUT</sub> = V <sub>CC</sub> or GND, DE = 0V			±20	μΑ
I <sub>OFF</sub>	Power Off Output Current	V <sub>CC</sub> = 0V, V <sub>OUT</sub> = 0V or 3.6V			±20	μΑ
Ios	Short Circuit Output Current	$V_{OUT} = 0V$ , $DE = V_{CC}$			-8	mA
		$V_{OD} = 0V$ , $DE = V_{CC}$			±8	
LVTTL Driv	er Characteristics					
V <sub>OH</sub>	Output HIGH Voltage	$I_{OH} = -100 \mu\text{A}, \overline{\text{RE}} = 0\text{V},$				V
OH		See Figure 6 and Table 1	V <sub>CC</sub> -0.2			
		$I_{OH} = -8 \text{ mA}, \overline{RE} = 0V, V_{ID} = 400 \text{ mV}$				
		$V_{ID} = 400 \text{ mV}, V_{IC} = 1.2 \text{V}, \text{ see Figure 6}$	2.4			
V <sub>OL</sub>	Output LOW Voltage	$I_{OL} = 100 \mu A, \overline{RE} = 0V, V_{ID} = -400 \text{ mV}$				
		See Figure 6 and Table 1			0.2	
		$I_{OI} = -8 \text{ mA}, \overline{RE} = 0V, V_{ID} = -400 \text{ mV}$				V
		$V_{ID} = -400$ mV, $V_{IC} = 1.2$ V, see Figure 6			0.5	
I <sub>OZ</sub>	Disabled Output Leakage Current	$V_{OUT} = V_{CC}$ or GND, $\overline{RE} = V_{CC}$			±20	μА
LVDS Rece	iver Characteristics			I		
$V_{TH}$	Differential Input Threshold HIGH	See Figure 6 and Table 1			100	mV
V <sub>TL</sub>	Differential Input Threshold LOW	See Figure 6 and Table 1	-100			mV
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = 0V or V <sub>CC</sub>			±20	μΑ
I <sub>I(OFF)</sub>	Power-OFF Input Current	V <sub>CC</sub> = 0V, V <sub>IN</sub> = 0V or 3.6V			±20	μА
LVTTL Driv	er and Control Signals Characteristi	cs				
V <sub>IH</sub>	Input HIGH Voltage		2.0		V <sub>CC</sub>	V
V <sub>IL</sub>	Input LOW Voltage		GND		0.8	V
I <sub>IN</sub>	Input Current	V <sub>IN</sub> = 0V or V <sub>CC</sub>			±20	μΑ
I <sub>I(OFF)</sub>	Power-OFF Input Current	V <sub>CC</sub> = 0V, V <sub>IN</sub> = 0V or 3.6V			±20	μΑ
V <sub>IK</sub>	Input Clamp Voltage	I <sub>IK</sub> = -18 mA	-1.5			V

#### DC Electrical Characteristics (Continued) Device Characteristics Power Supply Current Driver Enabled, Driver Load: $R_L = 100 \Omega$ $I_{CC}$ 12.5 Receiver Disabled, No Receiver Load Driver Enabled, Driver Load: $R_L = 100 \Omega$ , Receiver Enabled, ( $R_{IN+} = 1V$ and $R_{IN-} = 1.4V$ ) 12.5 mΑ or ( $R_{IN+}$ = 1.4V and $R_{OUT-}$ = 1V) Driver Disabled, Receiver Enabled, $(R_{IN+} = 1V \text{ and } R_{IN-} = 1.4V) \text{ or }$ 7.0 $(R_{IN+}\,{=}\,1.4V$ and $R_{IN-}\,{=}\,1V)$ Driver Disabled, Receiver Disabled 7.0 mΑ Input Capacitance Any LVTTL or LVDS Input pF C<sub>OUT</sub> Output Capacitance Any LVTTL or LVDS Output 6 pF

**Note 2:** All typical values are at  $T_A = 25^{\circ}C$  and with  $V_{CC} = 3.3V$ .

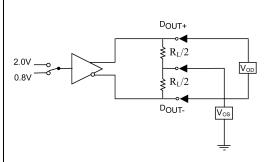
### **AC Electrical Characteristics**

Over supply voltage and operating temperature ranges, unless otherwise specified

Symbol	Parameter	Test Conditions	Min	Typ (Note 3)	Max	Units
Driver Timi	ng Characteristics	L	I			
t <sub>PLHD</sub>	Differential Propagation Delay		0.5		1.5	ns
	LOW-to-HIGH		0.5		1.5	115
t <sub>PHLD</sub>	Differential Propagation Delay		0.5		1.5	ns
	HIGH-to-LOW	$R_L = 100 \Omega, C_L = 10 pF,$	0.5		1.5	115
t <sub>TLHD</sub>	Differential Output Rise Time (20% to 80%)	See Figure 2 and Figure 3	0.4		1.0	ns
t <sub>THLD</sub>	Differential Output Fall Time (80% to 20%)		0.4		1.0	ns
t <sub>SK(P)</sub>	Pulse Skew  t <sub>PLH</sub> - t <sub>PHL</sub>				0.5	ns
t <sub>SK(PP)</sub>	Part-to-Part Skew (Note 4)				1.0	ns
t <sub>ZHD</sub>	Differential Output Enable Time from Z to HIGH	$R_L = 100\Omega$ , $C_L = 10$ pF,			5.0	ns
t <sub>ZLD</sub>	Differential Output Enable Time from Z to LOW	See Figure 4 and Figure 5			5.0	ns
t <sub>HZD</sub>	Differential Output Disable Time from HIGH to Z				5.0	ns
t <sub>LZD</sub>	Differential Output Disable Time from LOW to Z				5.0	ns
Receiver Ti	iming Characteristics					
t <sub>PLH</sub>	Propagation Delay LOW-to-HIGH		0.9		2.5	ns
t <sub>PHL</sub>	Propagation Delay HIGH-to-LOW		0.9		2.5	ns
t <sub>TLH</sub>	Output Rise time (20% to 80%)	$ V_{ID}  = 400 \text{ mV}, C_L = 10 \text{ pF},$		0.5		ns
t <sub>THL</sub>	Output Fall time (80% to 20%)	See Figure 6 and Figure 7		0.5		ns
t <sub>SK(P)</sub>	Pulse Skew   t <sub>PLH</sub> - t <sub>PHL</sub>				0.5	ns
t <sub>SK(PP)</sub>	Part-to-Part Skew (Note 4)				1.0	ns
t <sub>ZH</sub>	LVTTL Output Enable Time from Z to HIGH				5.0	ns
t <sub>ZL</sub>	LVTTL Output Enable Time from Z to LOW	$R_L = 500 \Omega$ , $C_L = 10 pF$ ,			5.0	ns
t <sub>HZ</sub>	LVTTL Output Disable Time from HIGH to Z	See Figure 8			5.0	ns
t <sub>LZ</sub>	LVTTL Output Disable Time from LOW to Z				5.0	ns

Note 3: All typical values are at  $T_A = 25^{\circ}C$  and with  $V_{CC} = 5V$ .

Note 4: t<sub>SK(PP)</sub> is the magnitude of the difference in propagation delay times between any specified terminals of two devices switching in the same direction (either LOW-to-HIGH or HIGH-to-LOW) when both devices operate with the same supply voltage, same temperature, and have identical test circuits.



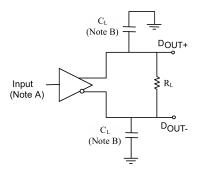
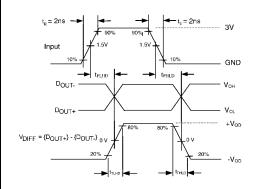
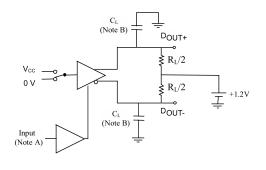


FIGURE 1. Differential Driver DC Test Circuit

 $\label{eq:Note A: Input pulses have frequency = 10 MHz, $t_R$ or $t_F$ = 2 ns} \\ \mbox{Note B: $C_L$ includes all probe and fixture capacitances}$ 

FIGURE 2. Differential Driver Propagation Delay and Transition Time Test Circuit





Note B: Input pulses have the frequency = 10 MHz,  $t_{R}$  or  $t_{F}$  = 2 ns

Note A: C<sub>L</sub> includes all probe and fixture capacitances

FIGURE 3. AC Waveforms for Differential Driver

FIGURE 4. Differential Driver Enable and Disable Test Circuit

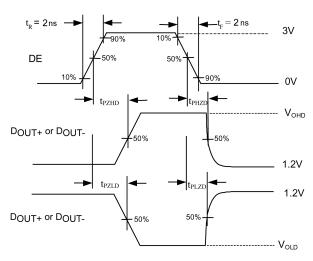
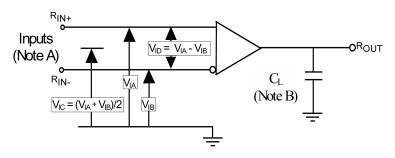


FIGURE 5. Enable and Disable AC Waveforms



Note A: Input pulses have frequency = 10 MHz,  $t_R$  or  $t_F$  = 1ns

Note B:  $C_L$  includes all probe and fixture capacitance

FIGURE 6. Differential Receiver Voltage Definitions and Propagation Delay and Transition Time Test Circuit

TABLE 1. Receiver Minimum and Maximum Input Threshold Test Voltages

Applied Voltages (V)		Resulting Differential Input Voltage (mV)	Resulting Common Mode Input Voltage (V)		
V <sub>IA</sub>	V <sub>IB</sub>	V <sub>ID</sub>	V <sub>IC</sub>		
1.25	1.15	100	1.2		
1.15	1.25	-100	1.2		
2.4	2.3	100	2.35		
2.3	2.4	-100	2.35		
0.1	0	100	0.05		
0	0.1	-100	0.05		
1.5	0.9	600	1.2		
0.9	1.5	-600	1.2		
2.4	1.8	600	2.1		
1.8	2.4	-600	2.1		
0.6	0	600	0.3		
0	0.6	-600	0.3		

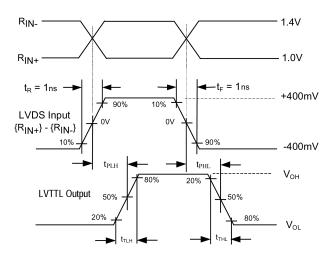
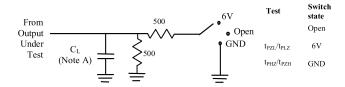


FIGURE 7. LVDS Input to LVTTL Output AC Waveforms

### **Test Circuit for LVTTL Outputs**



### Voltage Waveforms Enable and Disable Times

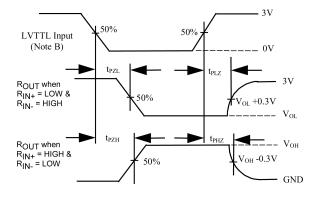


FIGURE 8. LVTTL Outputs Test Circuit and AC Waveforms

# **DC / AC Typical Performance Curves**

### Drivers

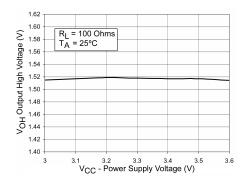


FIGURE 9. Output High Voltage vs. Power Supply Voltage

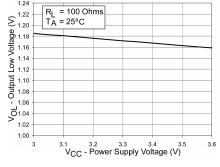


FIGURE 10. Output Low Voltage vs. Power Supply Voltage

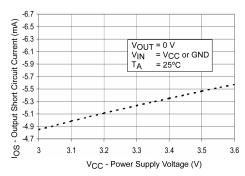


FIGURE 11. Output Short Circuit Current vs.
Power Supply Voltage

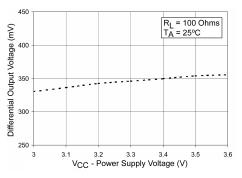


FIGURE 12. Differential Output Voltage vs. Power Supply Voltage

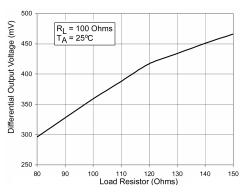


FIGURE 13. Differential Output Voltage vs. Load Resistor

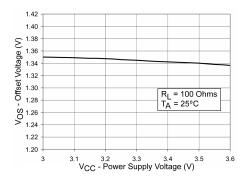
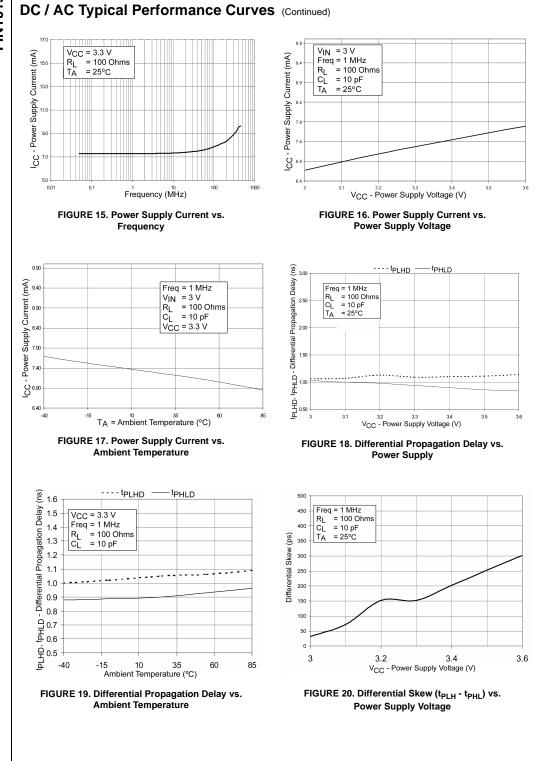
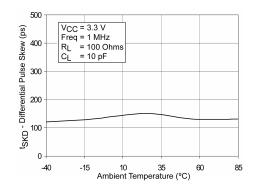


FIGURE 14. Offset Voltage vs. Power Supply Voltage



# DC / AC Typical Performance Curves (Continued)



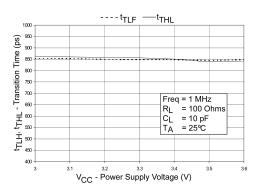


FIGURE 21. Differential Pulse Skew ( $t_{PLH}$  -  $t_{PHL}$ ) vs. Ambient Temperature

FIGURE 22. Transition Time vs. Power Supply Voltage

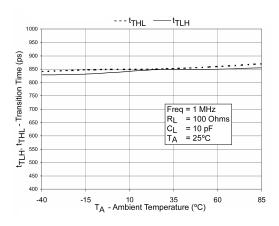
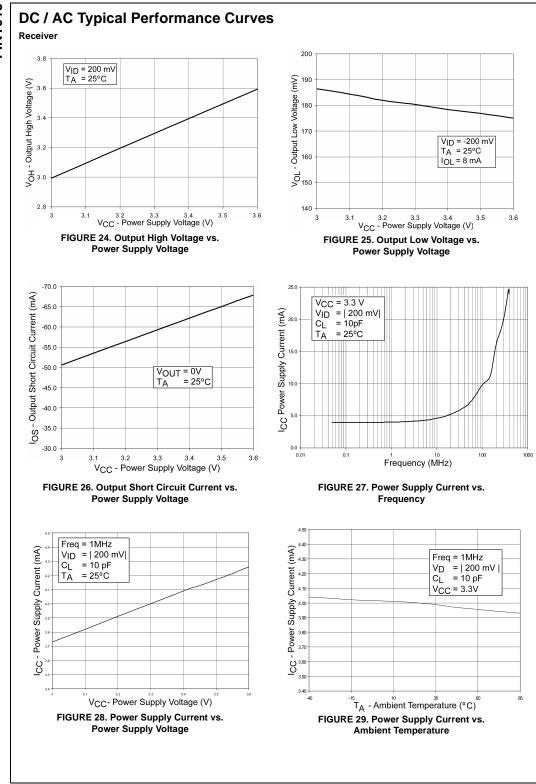
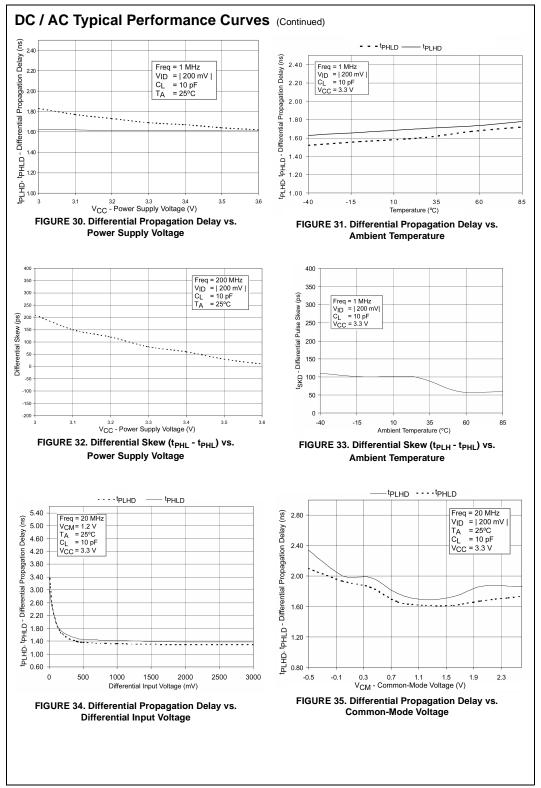


FIGURE 23. Transition Times vs.
Ambient Temperature





# DC / AC Typical Performance Curves (Continued)

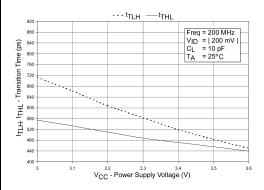


FIGURE 36. Transition Time vs. Power Supply Voltage

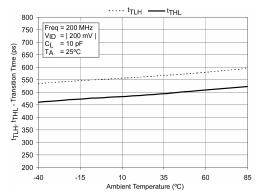


FIGURE 37. Transition Time vs. Ambient Temperature

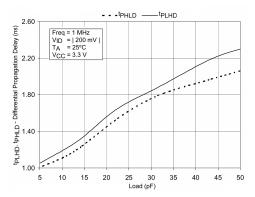


FIGURE 38. Differential Propagation Delay vs. Load

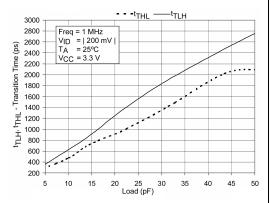
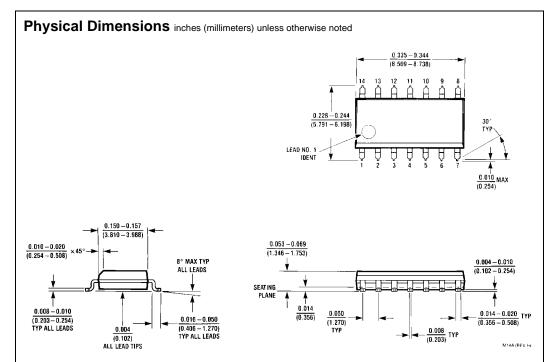
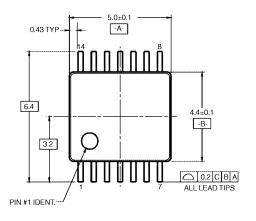


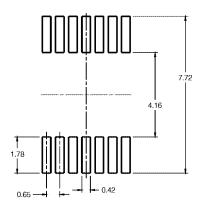
FIGURE 39. Transition Time vs. Load



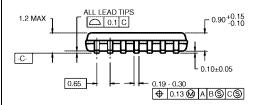
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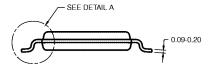
### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)





LAND PATTERN RECOMMENDATION

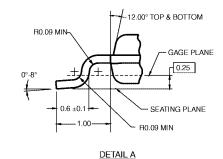




NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

MTC14RevC3



14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

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- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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